Preface

The publication of the 2001 Supplement to the *Microelectronic Failure Analysis Desk Reference*, 4th edition, is intended as an update to this original source material and also provides the opportunity to introduce new topics. The development of this Supplement has been the work of multiple individuals.

The articles were written by a number of authors and coauthors, who are credited in the bylines to their articles. Their work was coordinated by chapter overseers for the four primary topic areas addressed in the Supplement:

- AFM/SCM/SPM (Terry Kane, IBM)
- Copper Deprocessing (David Su, TSMC)
- Package/Sample Cross Sectioning (Brett Engel, IBM)
- FIB Backside Isolation Techniques (Ted Hasegawa, National Semiconductor)

Chris Henderson of Sandia National Laboratories generously updated the key word index for the ISTFA Proceedings through ISTFA 2000 and also incorporated key words from the *Microelectronic Failure Analysis Desk Reference*, 4th edition. Robert Lowry has contributed a useful glossary of failure analysis tool acronyms.

The efforts of multiple individuals to review the technical content and to provide editing corrections on the individual papers also added immeasurably to the final version of this Supplement. In particular, Stan Silvus of Southwest Research Institute, Jerry Soden of Sandia National Laboratories, Chuck Hawkins of University of New Mexico, Dan Barton of Sandia National Laboratories, Rebecca Holdford of Texas Instruments, and Ed Cole of Sandia National Laboratories were especially forthcoming with their time and assistance.

Special thanks are also due to EDFAS Publications Committee Vice Chair Don Staab (Xilinx) for his tireless efforts in editing articles and assisting to complete this Supplement.

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Terry Kane  
Chair  
EDFAS Publications Committee  
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